



Customer Information Notification

202204010I : PF0100A and PF0200A Data Sheet Updates - Package Drawing Optional Views Only

Note: This notice is NXP Company Proprietary.

Issue Date: May 27, 2022 **Effective date:** May 28, 2022

Change Category

- | | | | | |
|--|---|--|--|---|
| <input type="checkbox"/> Wafer
Fab
Process | <input type="checkbox"/> Assembly
Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test
Process | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer
Fab
Materials | <input type="checkbox"/> Assembly
Materials | <input type="checkbox"/> Mechanical
Specification | <input type="checkbox"/> Test
Equipment | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer
Fab
Location | <input type="checkbox"/> Assembly
Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test
Location | <input type="checkbox"/> Electrical
spec./Test
coverage |
| <input type="checkbox"/> Firmware | <input checked="" type="checkbox"/> Other: Data Sheet Update for Package Drawing
Optional Views Only | | | |

PCN Overview

Description

NXP Semiconductors announces the data sheet updates to revision 20.0 and 8.0 respectively, for the PF0100A and PF0200A Power Management IC products associated with this notification. The data sheets have been updated to include new, optional package drawing views only - absolutely no changes to production products or packages.

As captured in the revision history of each new data sheet:

Added 98ASA00405D optional bottom view page for E-type package as per CIN 202204010I

New PF0100A data sheet revision 20.0 is attached to this notice, and can be accessed at:
<https://www.nxp.com/docs/en/data-sheet/MMPF0100.pdf>

New PF0200A data sheet revision 8.0 is attached to this notice, and can be accessed at:
<https://www.nxp.com/docs/en/data-sheet/MMPF0200.pdf>

Reason

The data sheets have been updated to include new, optional package drawing views only.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

A new datasheet will be issued

Additional information

Additional documents: [view online](#)

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

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